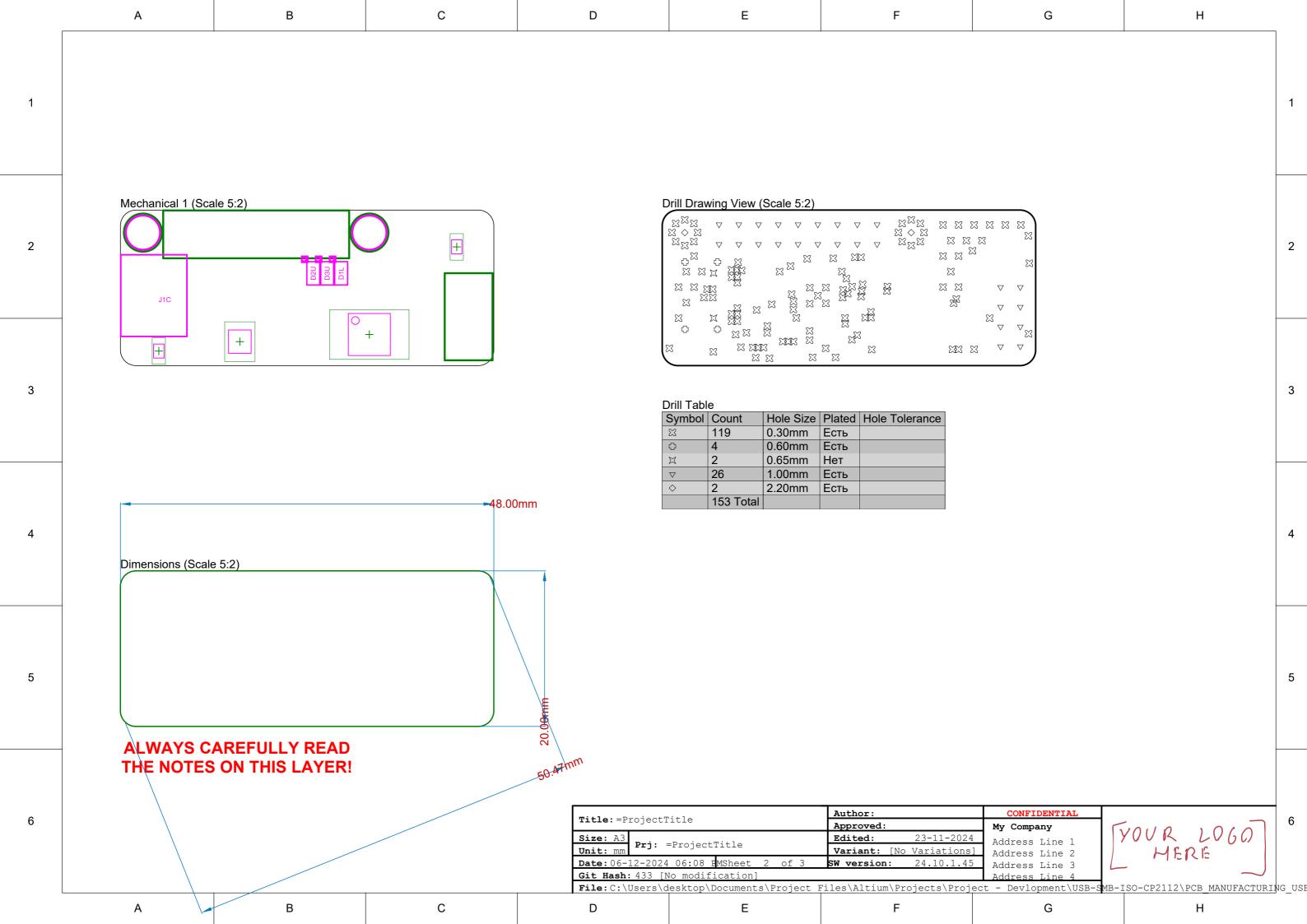
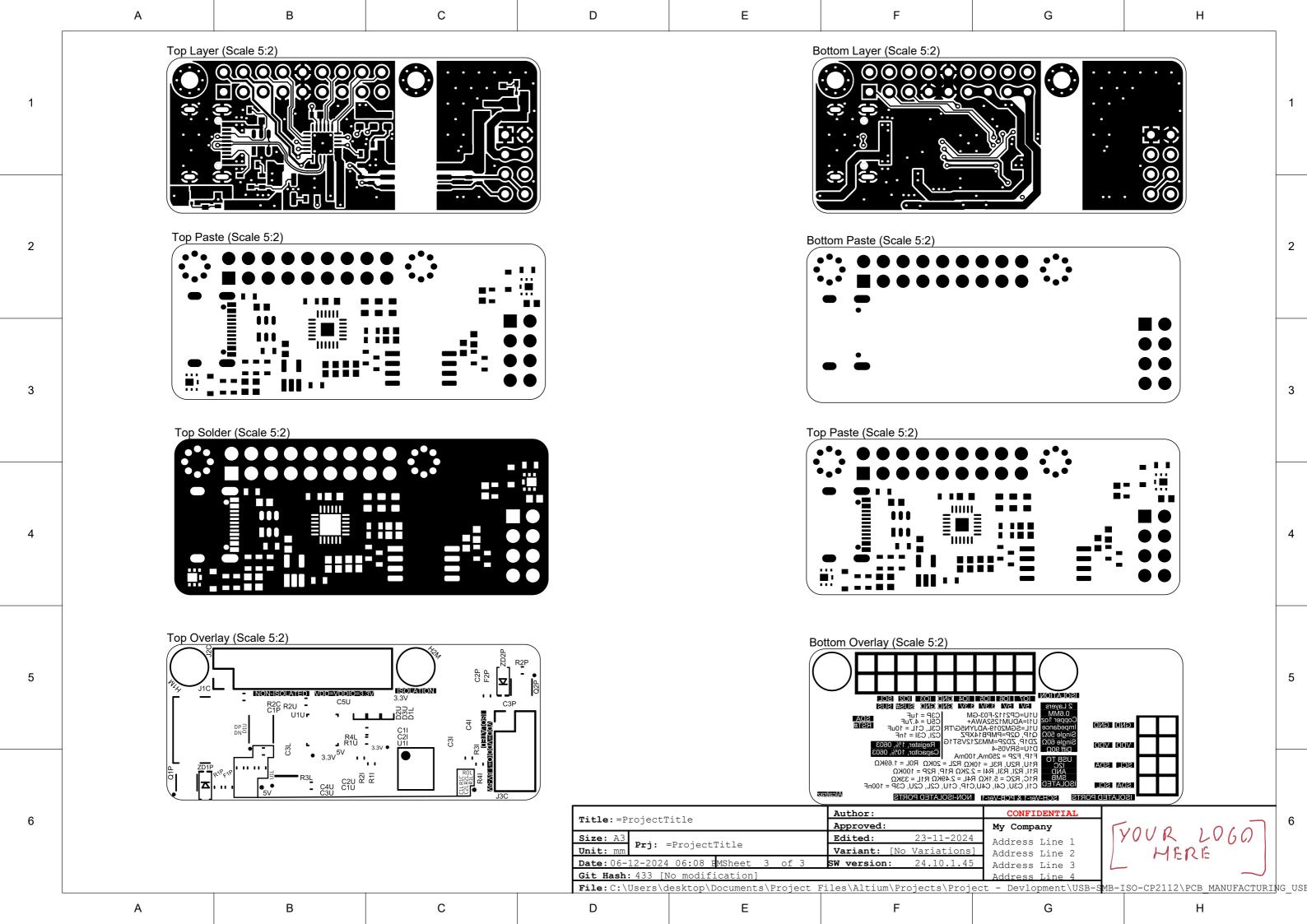
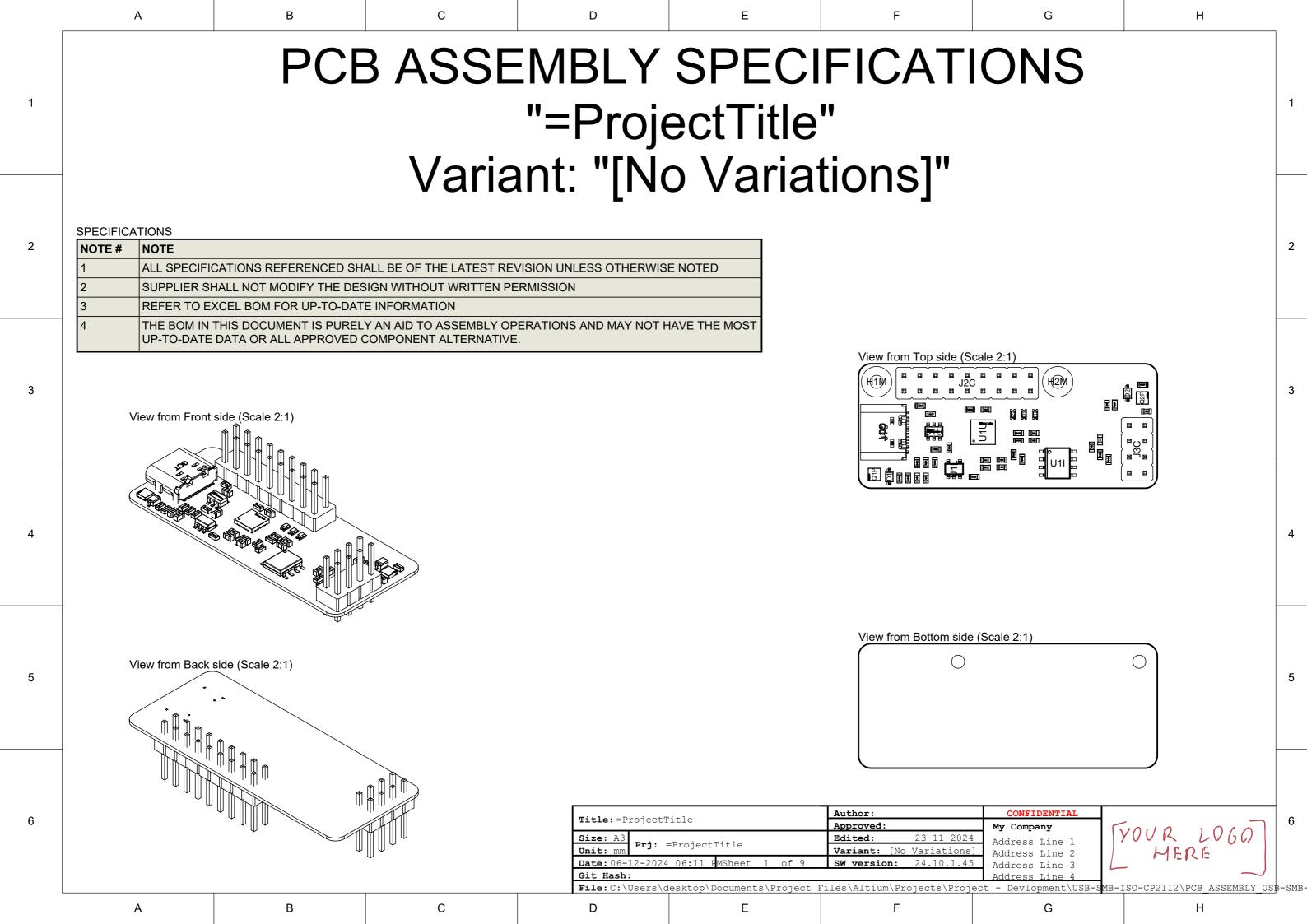
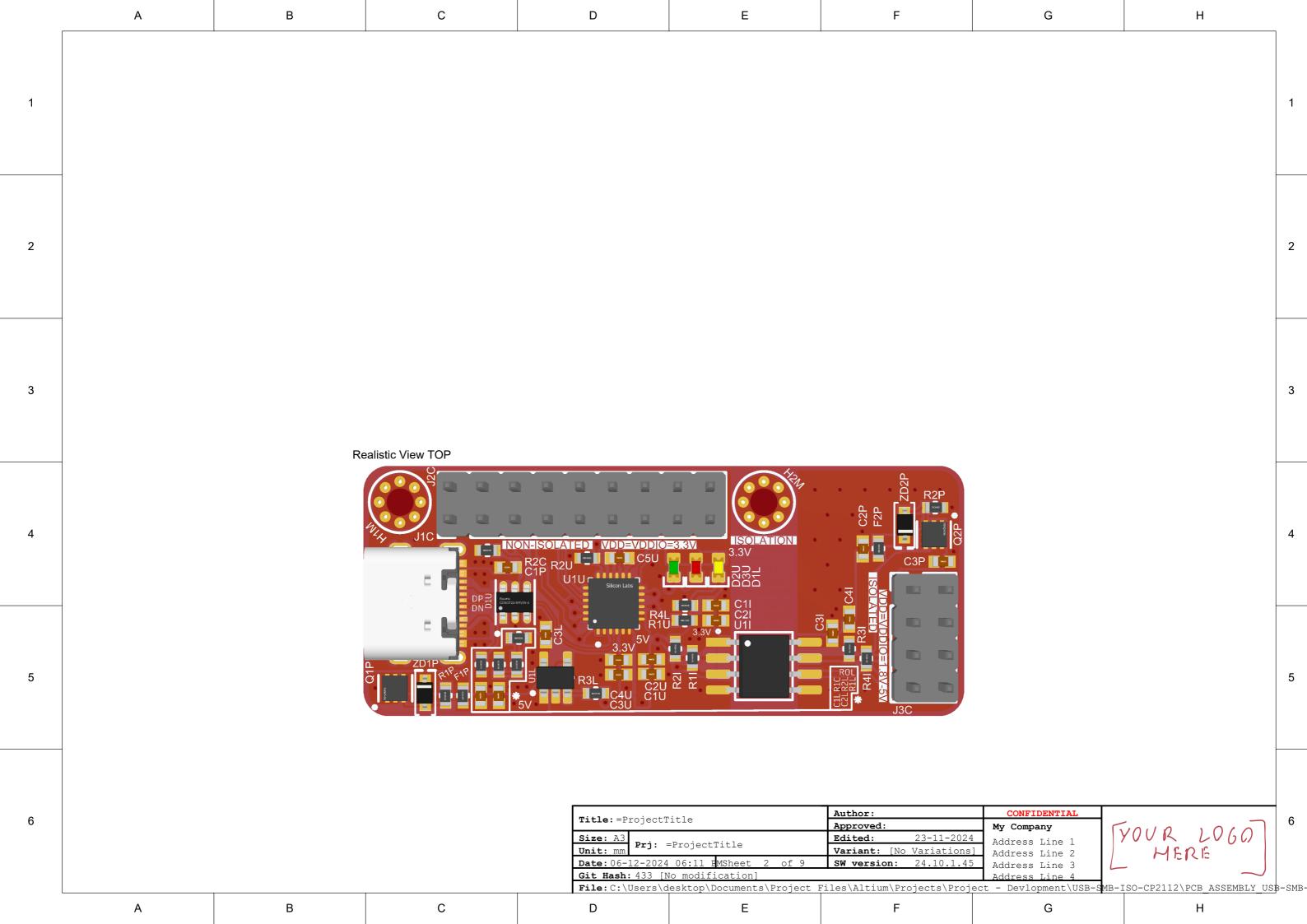


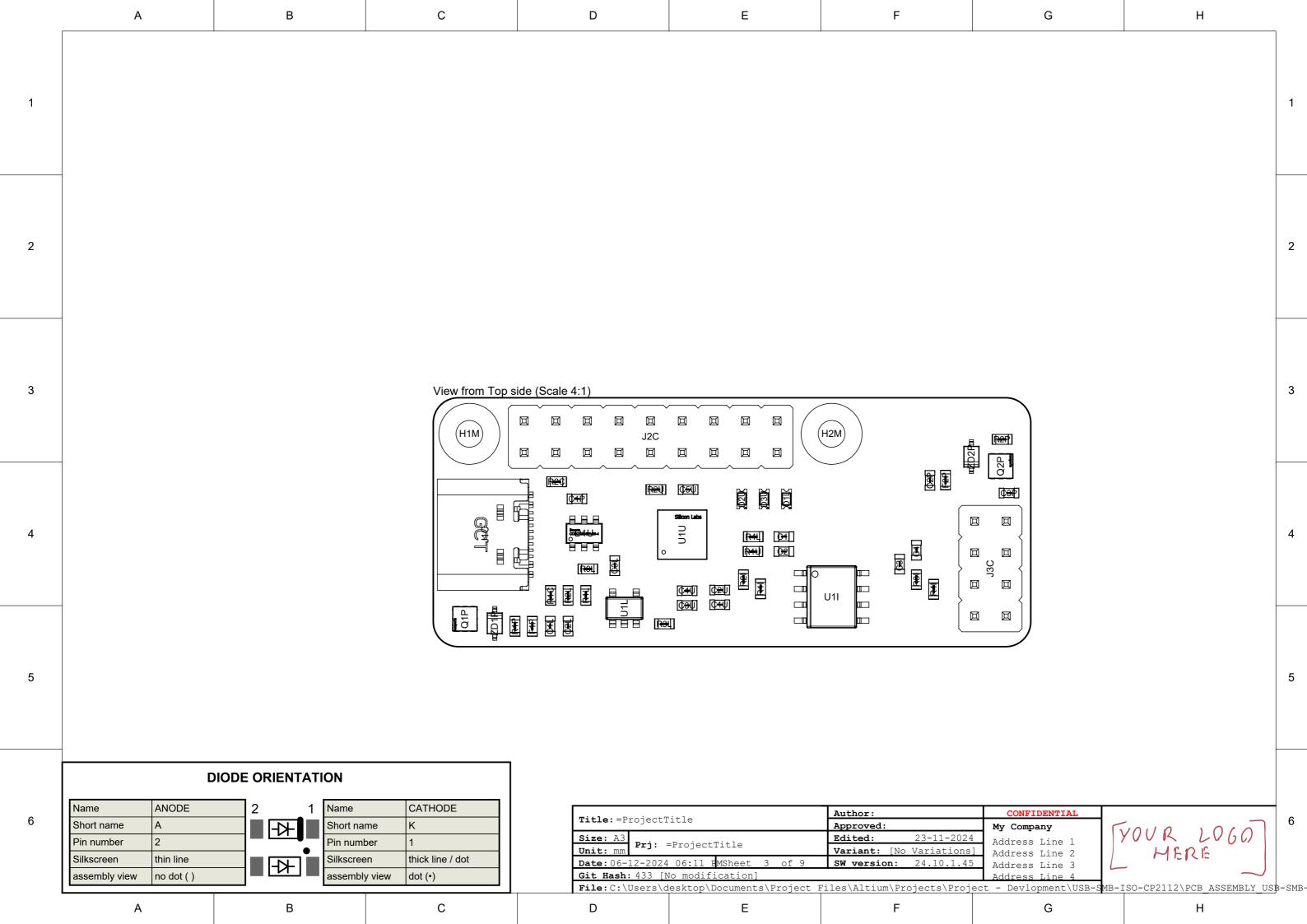
PCB MANUFACTURING SPECIFICATIONS "=ProjectTitle" **SPECIFICATIONS SPECIFICATIONS** NOTE# NOTE LENGHT 20.00mm **WIDTH** ALL SPECIFICATIONS REFERENCED ARE OF THE REVISION SPECIFIED IN THE TITLE BLOCK 48.00mm **LAYERS** SUPPLIER SHALL NOT MODIFY THE DESIGN OR APPROVED STACK-UP WITHOUT WRITTEN PERMISSION FR-4 **MATERIAL** ALL MATERIALS SHALL BE RoHS COMPLIANT AND FINAL PRODUCT SHALL BE ACCEPTABLE TO USE IN RoHS ASSEMBLY. RoHS LOGO SHALL BE MARKED IN SILKSCREEN INK BY THE SUPPLIER WHERE INDICATED BY **MATERIAL MIN TG** 130-140 THE TEXT "PLACE MARKINGS HERE" TRACK WIDTH/CLEARANCE 10 mils / 10 mils COPPER FOIL: REFER TO LAYER STACK LEGEND FOR Cu THICKNESS DETAILS. ALL Cu THICKNESSES ARE **THICKNESS** 0.6mm FINISHED AND INCLUDE BASE FOIL PLUS Cu PLATING ON PLATED LAYERS **COPPER THICKNESS** 35um (1oz) ELECTRICAL TEST: ALL PRINTED CIRCUITS SHALL BE 100% ELECTRICALLY TESTED FOR OPENS/SHORTS USING PROVIDED NETLIST. REJECTED PRINTED BOARDS MUST BE CLEARLY MARKED WITH NON-YES, TOP AND BOTTOM SOLDERMASK CONDUCTIVE. PERMANENT INK. **GREEN SOLDERMASK COLOR** MARKINGS: VENDOR MARKING AND DATE/LOT CODES SHALL BE LOCATED ON THE BOARD IN THE SILKSCREEN YES. TOP AND BOTTOM RESERVED AREA AS SPECIFIED IN THE GERBER LAYER "PCBM NOTES" BY THE TEXT "PLACE MARKINGS SILKSCREEN COLOR WHITE MARKINGS: THE SIDE ONTO WHICH PLACE THE MARKINGS IS AT THE SUPPLIER DISCRESSION UNLESS SURFACE FINISH **HASL LEAD FREE** OTHERWISE NOTED ONTO THE LAYER "PCBM NOTES" NO **GOLD FINGERS** SUPPLIER SHALL CHECK PCBM NOTES LAYER BEFORE ASKING FOR CLARIFICATIONS **CHAMFERING** YES MANUFACTURE TENTED/PLUGGED VIAS AS SPECIFIED IN THE GERBER FILES YES IMPEDANCE CONTROL HALF-CUT/CASTELLATED HOLES NO **BURIED/BLIND VIAS** NO NO VIAS FILLED WITH RESIN Layer Stack Legend Material Layer Thickness Dielectric Material Type Gerber NO **CARBON MASK** Top Overlay GTO COUNTERSINKS/COUNTERBORES NO Surface Material Top Solder Solder Mask GTS NO **Z-AXIS MILLING** Copper Top Layer Signal GTL PEELABLE SOLDERMASK NO Core 0.50mm FR-4 Dielectric **GBL** 0.04mm Signal Solder Mask GBS Surface Material Bottom Solder 0.02mm Solder Resist GBO **Bottom Overlay** Legend Total thickness: 0.60mm NON-COPPER LAYER THICKNESS FOR REFERENCE ONLY LAYERS OF TYPE "INTERNAL PLANE" ARE NEGATIVE Author: Title: =ProjectTitle Approved: My Company Prj: =ProjectTitle Address Line 1 Variant: Address Line 2 Date: 06-12-2024 SW version: Address Line 3 С G В

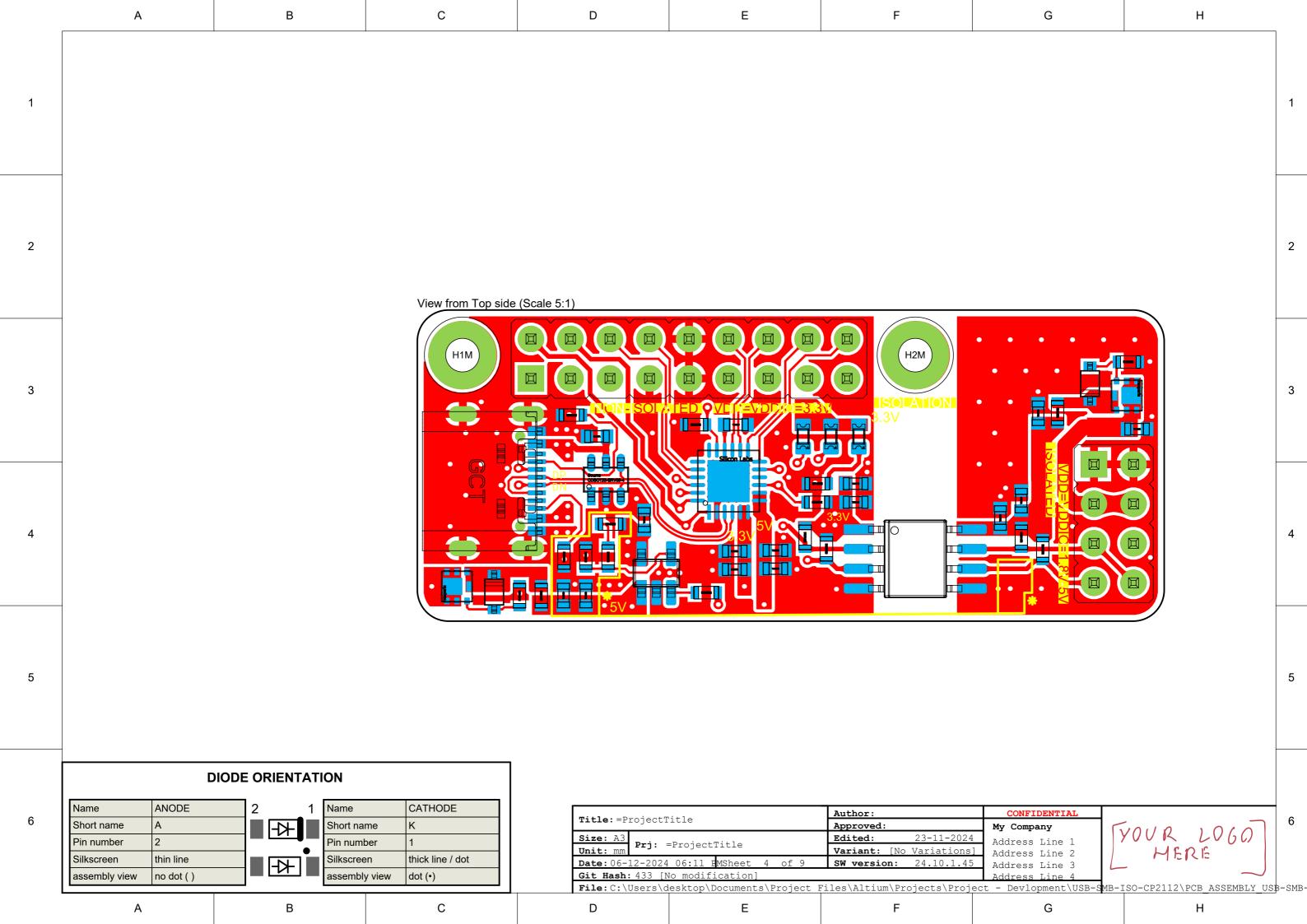


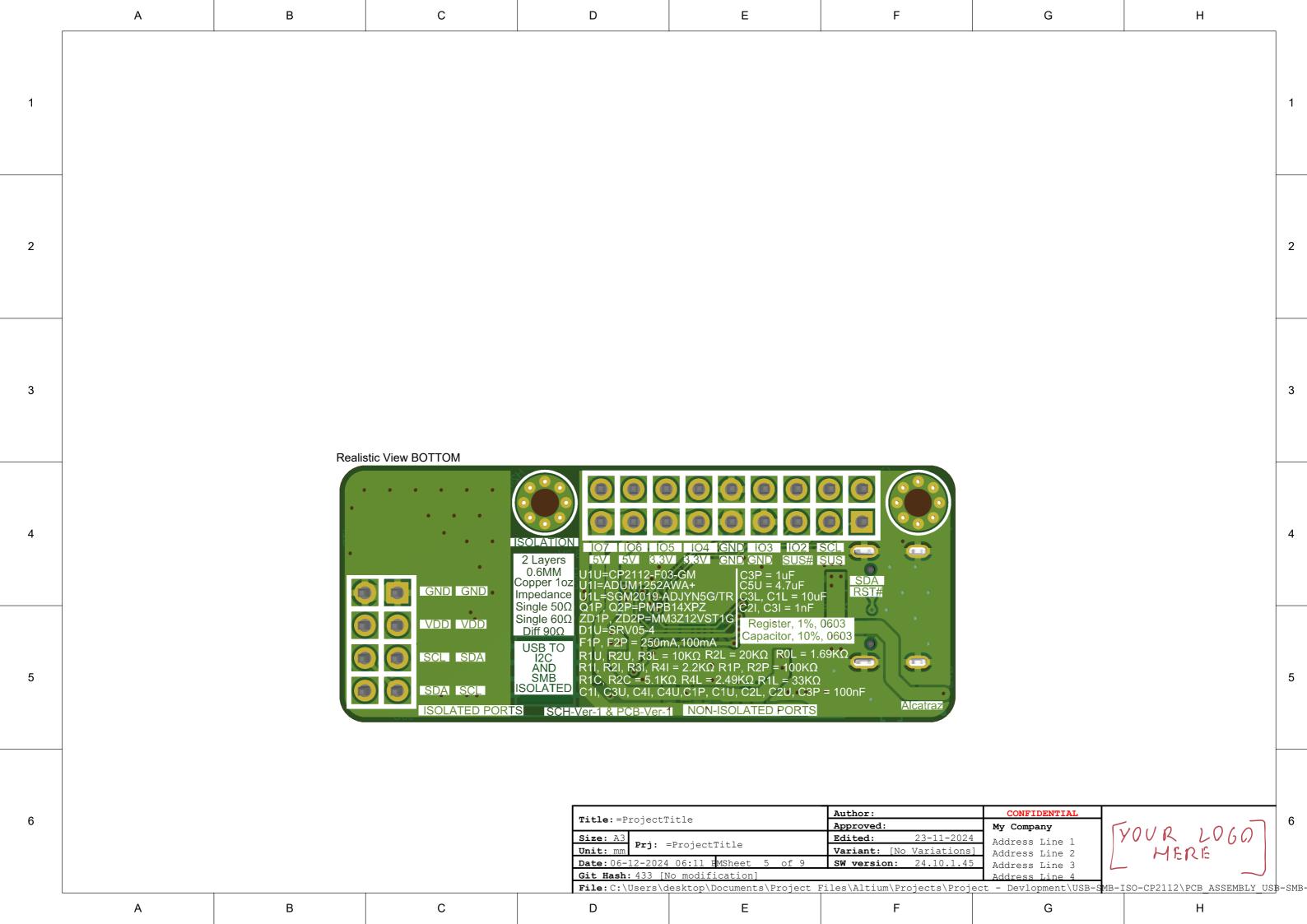


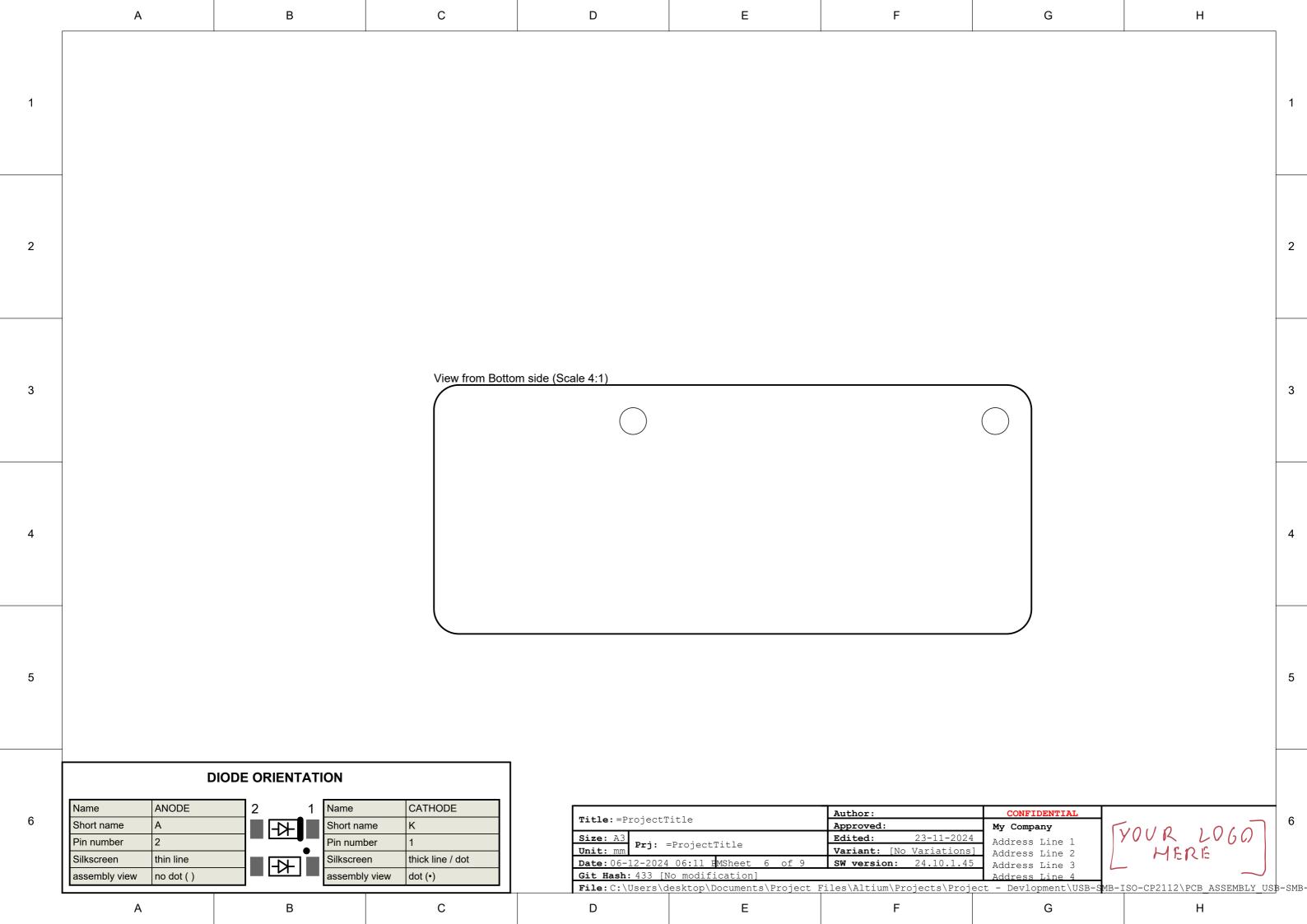


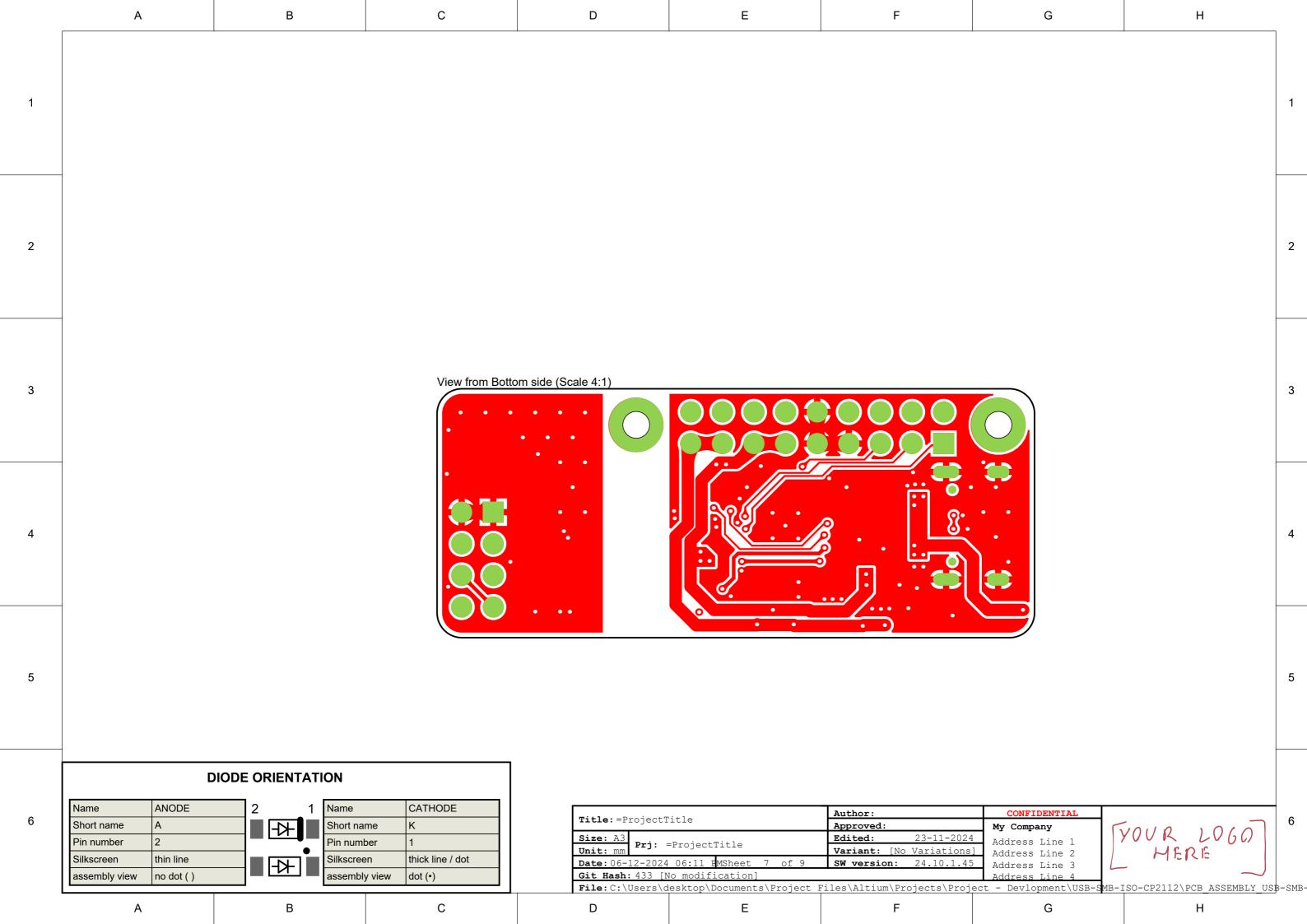


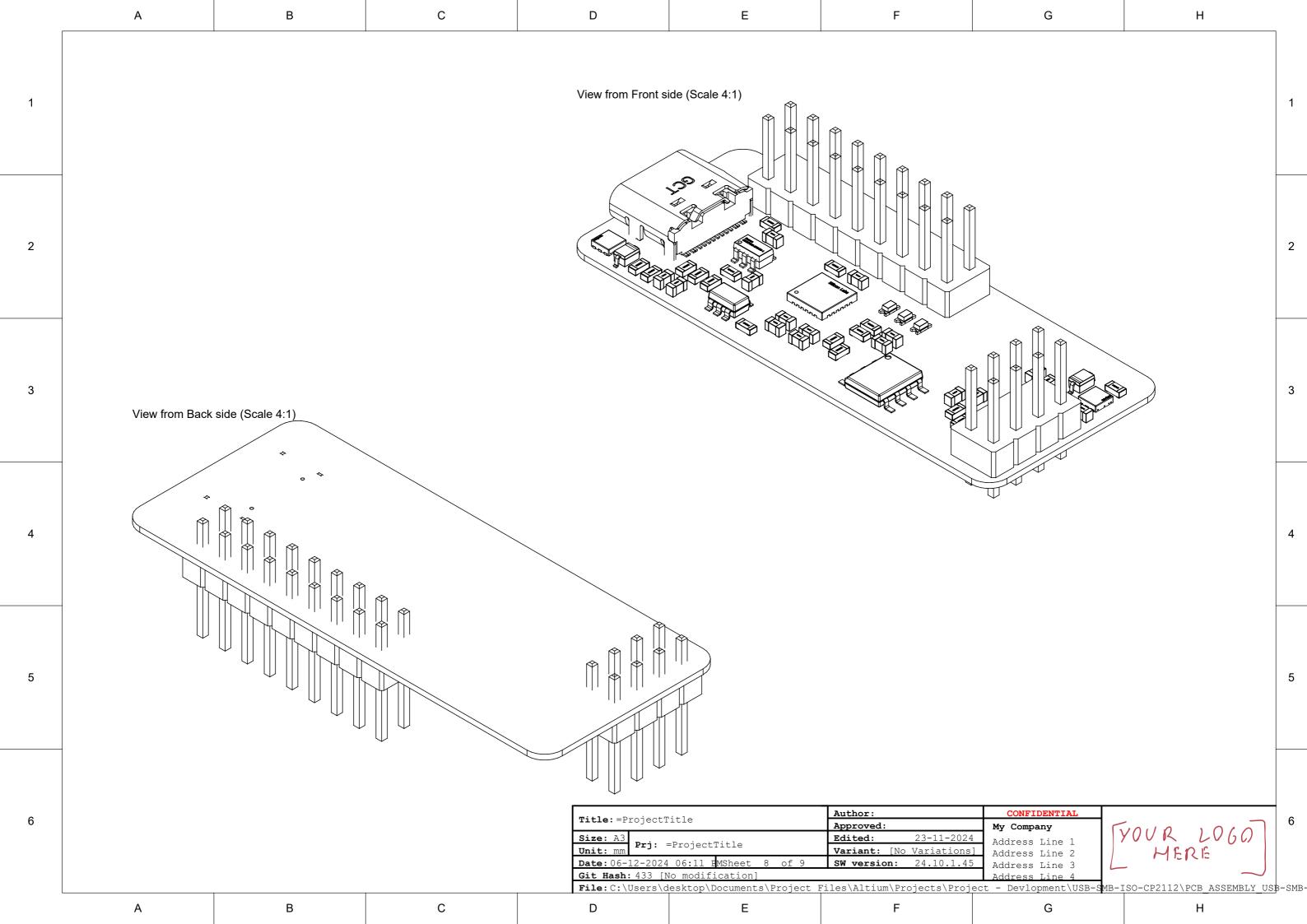












	,	А В	С	D	E	F	G	Н		
1								1		
	Bill Of M	aterials								
2	Line #			Designator	Quantity	Manufacturer Part Number 1	Part Number	Layer		
		Cap Cer 0.1UF 6.3V X7R 0603		C1I, C3U, C4I	U 3	KGM15AR70J104KM			2	
		Multilayer Ceramic Capacitor, 10 uF, 10 V, ± 10%, X5R, 0603 [1608 Metric]		C1L	1	C0603C104K8RAC786				
		Multilayer Ceramic Capacitor, 0.1 uF, 10 V, ± 10%, X7R, 0603 [1608 Metric] Cap Ceramic 0.001uF 6.3V C0G 10% SMD 0603 125°C Paper T/R Ceramic Capacitor, Multilayer, Ceramic, 10V, 10% +Tol, 10% -Tol, X5R, 15% TC,		C1P, C1U, C2L, C2U,	C3P, C4I 6	7				
				C2I C2P	1	06036A102KAT2A				
3		1uF, 0603 Cap Ceramic 0.001uF 10V X7R 10% SMD 0603 125°C Paper T/R Multilayer Ceramic Capacitor, 10 uF, 6.3 V, ± 10%, X5R, 0603 [1608 Metric]		C3I	1	CC0603KRX7R6BB102				
				C3L	1	CL10A106KQ8NNNC				
			Multilayer Ceramic Capacitor, 4.7 uF, 10 V, ± 10%, X5R, 0603 [1608 Metric] LED 0603 YELLOW SMD		C5U 1 CL10A475KP8NNNC D1L 1					
		TVS DIODE 5V 15	/ SOT23-6	D1U	1				3	
		LED 0603 GREEN SMD LED 0603 RED SMD		D2U D3U	1					
		Fuse PPTC SMD 0603 Fuse PPTC SMD 0603		F1P F2P	1					
		USB Connector Type		J1C	1					
		(Power pins joints = 12 pins)		J2C	1					
4				J3C	1					
		PMPB14XPZ Surface Mount Thick Film Chip Resistor 0603 Case 1.69K Ohms 1% Tolerance 100 PPM SMD Chip Resistor, 5.1 kOhm, ± 1%, 100 mW, 0603 [1608 Metric], Thick Film, General Purpose SMD Chip Resistor, 2.2 kOhm, ± 1%, 100 mW, 0603 [1608 Metric], Thick Film, General Purpose Res Thick Film 0603 33K Ohm 1% 0.1W(1/10W) ±100ppm/C Pad SMD Automotive		Q1P, Q2P	2	PMPB14XPZ			4	
				R0L	1	MCR03EZPFX1691				
				R1C, R2C		CRCW06035K10FKEA				
				R1I, R2I, R3I, F	R4I 4	RC0603FR-072K2L				
		SMD Chip Resistor, 100 kOhm, ± 1%, 100 r		R1L	1	ERJ-3EKF3302V			4 1	
5		General Pur SMD Chip Resistor, 10 kOhm, ± 1%, 100 n	oose	R1P, R2P	2	AC0603FR07100KL				
		General Purpose SMD Chip Resistor, 20 kOhm, ± 1%, 100 mW, 0603 [1608 Metric], Thick Film,		R1U, R2U, R3	3 4	RC0603FR-0710KL CR0603-FX-2002ELF				
		General Pur Res Thick Film 0603 2.49K Ohm 1% 1/10W ±		R2L	1	MCR03EZPFX2491				
		T/R Ultra-Low Power, Bidirectional I2C Isolator with Extended VDD, Idle-Bus Hot-Swap		U1I	1	ADUM1252AWA+			5	
		and Low V LDO U-Reg Adj 0, 3		U1L	1					
		IC HID USB-TO-SMBUS	BRIDGE 24QFN	U1U	1					
		MM3Z12VST1G Zener Diode, 12V 2% 200 mW SMT 2-Pin SOD-323 ON Semiconductor MM3Z12VST1G		ZD1P, ZD2P 2		MM3Z12VST1G				
6					·					
	Please consider LCSC (立创商城) as our first supplier BOM FOR REFERENCE ONLY ALWAYS REFER TO THE LATEST EXCEL BOM PROVIDED			Title: =ProjectTitle Size: A3 Unit: mm Date: 06-12-2024 06:11 PMSheet 9 of 9		Author: Approved:	CONFIDENTIAL My Company		<u> </u>	
						Edited: 23-11-20	My Company Address Line 1	YOUR LOGO	<i>)</i>	
						Variant: [No Variation SW version: 24.10.1.	Address Line 2	MERE		
				Git Hash: 433 [1	No modification]	Address Line 4			\rightarrow	
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